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ELECTRONICS MANUFACTURING ASIA INNOVATION AWARDS 2007
OFFICIAL ENTRY FORM

To qualify, please note the following:

1. All manufacturing related products, materials and equipment submitted must be introduced and offered for sale between 1 March 2006 and 31 December 2006 in Asia.
2. All sections must be completed. Incomplete entries will be disqualified by the judges.
3. All entries must be accompanied with this form in English.
4. Entries must reach us by **31 January 2007**. Please see Section G for submission guidelines.

A. COMPANY INFORMATION

Company Name:	
Contact:	
Job Title:	
Mailing Address:	
Postal Code:	
City:	
Country:	
Tel:	
Fax:	
Mobile:	
Email Address:	

B. AWARD CATEGORIES

(Tick as many as you would like; entry fee is USD500 per category.)

	<p>Adhesive/Coating/Encapsulating Materials This category includes conductive and non-conductive adhesives; water and solvent based conformal coatings and encapsulants used to embed and isolate electronic circuitry.</p>
	<p>Assembly Line Tools This category includes workstations, hand-tools, material handling equipment used on the production line.</p>
	<p>Cleaning Equipment This category includes cleaning equipment using aqueous, solvent based or ultrasonic cleaning methods.</p>
	<p>Cleaning Materials This category includes water and solvent based cleaning materials.</p>
	<p>Contract Services This category includes the provision of contract manufacturing services to original equipment manufacturers (OEMs). This includes the design, test, manufacturing and distribution, as well as providing return/repair services, of electronic component and assemblies.</p>
	<p>Dispensing Systems/Equipment This category includes manual, semi-automatic and automatic dispensers of adhesives, encapsulants and other interconnection materials.</p>
	<p>Environmentally friendly products/services This category includes products and services that contribute most towards pollution control, and waste disposal and recycling.</p>
	<p>Identification (ID) Systems This category includes coding, printing and laser marking systems and accessories for the identification of components, sub-assemblies and finished products.</p>
	<p>Inspection Equipment – AOI This category includes semi-automatic and automatic systems used for the optical inspection of printed circuit assemblies.</p>
	<p>Inspection Equipment - X-ray This category includes semi-automatic and automatic systems used for the x-ray inspection of printed circuit assemblies</p>
	<p>Manual Soldering Equipment This category includes soldering/desoldering irons and stations.</p>
	<p>Pick and Place Systems – Automated This category includes automatic placement machines used in volume manufacturing.</p>
	<p>Pick and Place Systems – Semiautomatic/Manual This category includes semi-automatic and manual placement machines used in prototyping or volume manufacturing.</p>
	<p>Programming This category includes manual, semi-automatic and automatic device programmers for online and offline applications.</p>

	<p>Reflow Soldering Equipment This category includes reflow ovens used in the soldering process.</p>
	<p>Repair/Rework Equipment This category includes manual, semi-automatic and automatic rework systems for soldered components.</p>
	<p>Screen Printing Equipment This category includes semi-automatic and automatic printing machines.</p>
	<p>Software This category includes software used to optimize equipment performance.</p>
	<p>Soldering Materials This category includes SnPb and Lead-free solders and other interconnection products.</p>
	<p>Test Equipment This category includes ICT, Boundary Scan, Functional Test and other types of automated test equipment.</p>
	<p>Wave Soldering Equipment This category includes wave soldering equipment used in the soldering process.</p>

C. PRODUCT INFORMATION (UP TO 250 WORDS)

Your submission must cover the following aspects of your product:

- Innovation
- Cost effectiveness
- Speed/Throughput improvements
- Quality Contribution
- Ease of use
- Maintainability and repairability
- Technology advancement

Please submit the information on a separate sheet.

D. OTHER REQUIRED DOCUMENTS

- A PDF or word file on technical specifications documenting a service program along with appropriate customer approval letter
- High resolution product image (300 dpi and above)
- Company name and standard product or service description to be used for judging and award purposes.

H. CERTIFICATION

We certify that the information submitted in this entry form is true and its contents have been approved by authorized personnel for submission to the Electronics Manufacturing Asia Innovation Awards 2007.

We agree to the terms and conditions of the Awards and understand the information submitted here may be made known to the public. We also understand should the information given here be proven untrue, this entry may be disqualified, even if it has been selected as a winner.

Nomination is submitted by (please endorse with official company stamp):

Name: _____

Job title: _____

Signature: _____ **Date:** _____